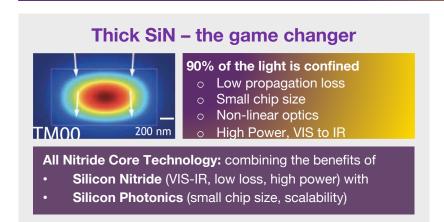
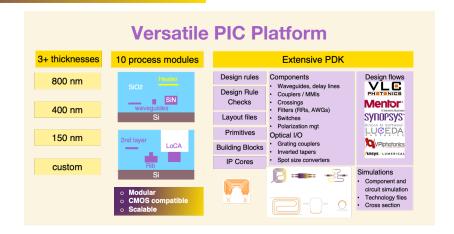




### **LIGENTEC Snapshot**





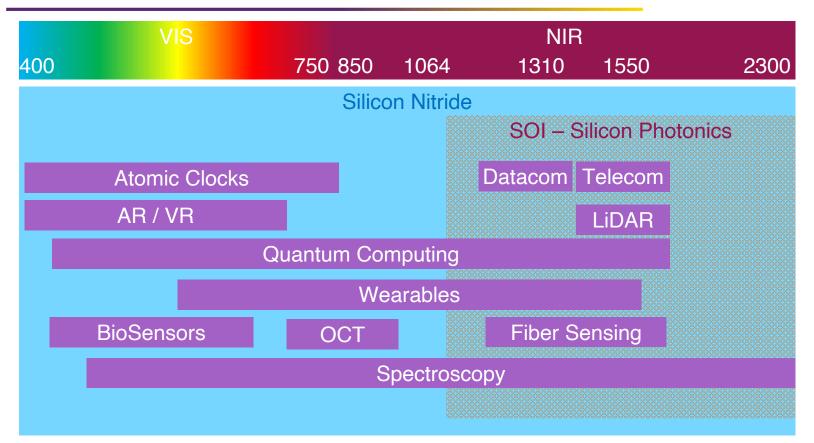






### Application requirement diversity: wavelength





### Photonic Integration: Motivation for low loss PICs

### Why are losses important?



- Long delay lines require of 10s of cm
- Detection of photons coming back
- Phase noise is related to losses

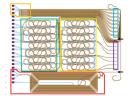


- Phase noise of AWGs is related to losses
- Tunable narrow linewidth lasers
- Narrow linewidth Filter



- Assymetric MZI interferometers
- High Q ring resonators
- Every photon counts

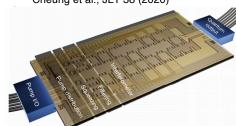




Martin et al., JLT 36 (2018)



Cheung et al., JLT 38 (2020)



Arrazola et al., Nature 54 March 2021

### **Versatile Platform**



3+ thicknesses

10 process modules

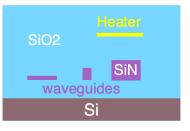
Extensive PDK

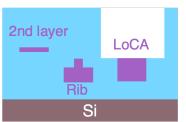
800 nm

400 nm

150 nm

custom





Design Rule Checks

Design rules

Layout files

Primitives

**Building Blocks** 

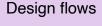
IP Cores



- Waveguides, delay lines
- · Couplers / MMIs
- Crossings
- Filters (RRs, AWGs)
- Switches
- Polarization mgt

### Optical I/O

- Grating couplers
- Inverted tapers
- Spot size converters





Component simulations



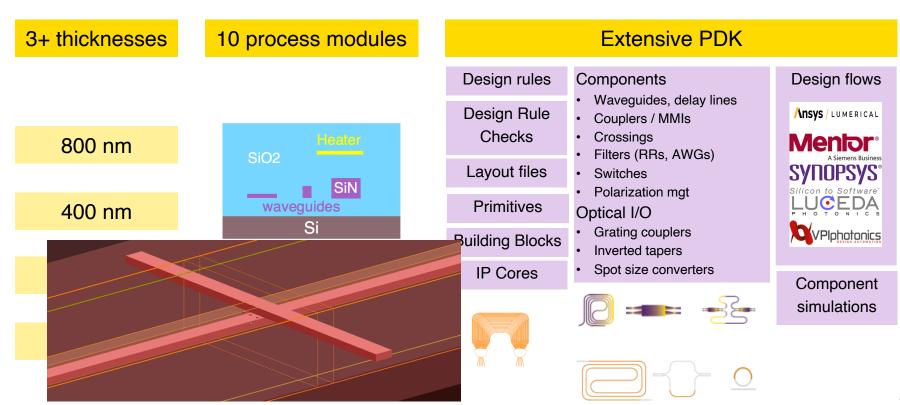




### A base to build on

### **Versatile Platform**





### One base – many options:

### SiN – The platform for monolithic & heterogeneous integration



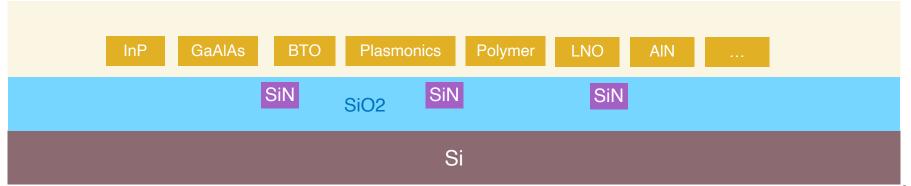
### **Use SiN as base platform for general circuitry**

- Comprehensive PDK
- Standard I/Os
- Scalable to volume

Add materials as required by application

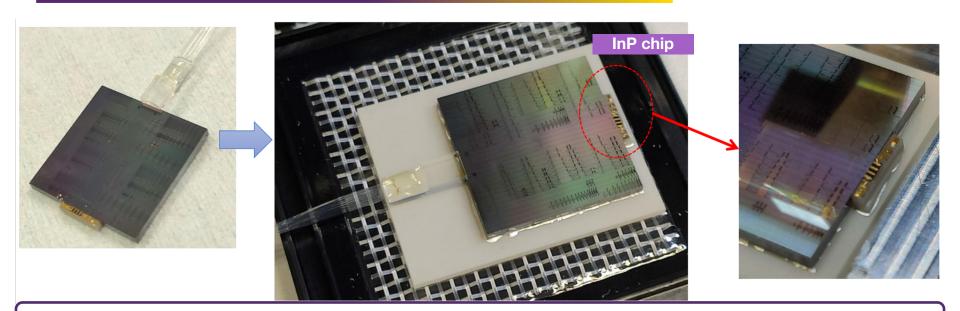
### Focus on wafer level integration e.g.:

- Monolithic integration
- Wafer bonding
- Micro Transfer Printing



# Hybrid Integration example InP Chip to passive SiN PIC





- SiN chip with FAU and SOA attached to it
- Assembly is glued on a ceramic carrier
- Requires flat and smooth chip facets

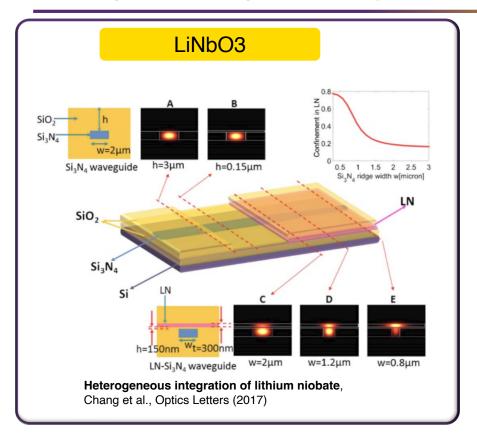
### **Hybrid integrated lasers**

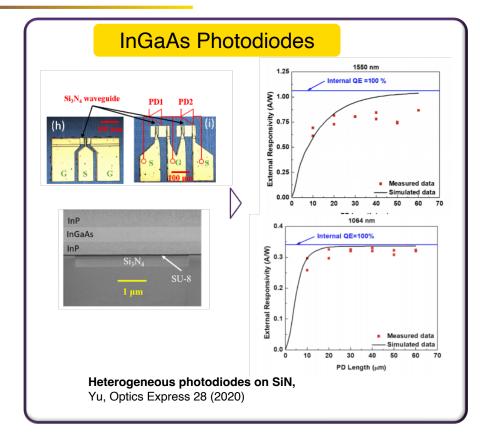
- Calo et al., OFC 2022
- Guo et al., IEEE Xplore (2021)

### LIGENTEC platform

### **Heterogeneous Integration examples**









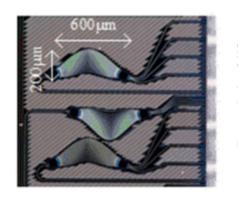
### **Communications**



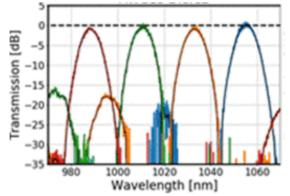
### Applications – Communications

### **Arrayed Waveguide Gratings (AWG)**





- ✓ low temperature dependence
- √ good process tolerance
- √ scalable
- ✓ Low phase errors
- √ small footprint



### **Gaussian AWG**

< -35 dB crosstalk

< 0.5 dB insertion loss

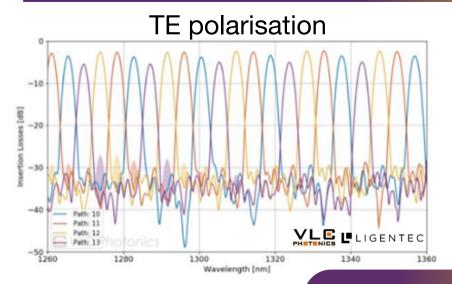
STD around 0.5nm

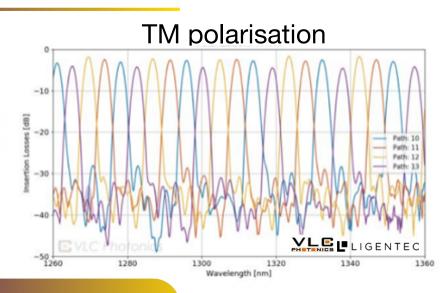
Cheung et al., JLT 38 (2020)

### Applications – Communications

### **Arrayed Waveguide Gratings (AWG)**





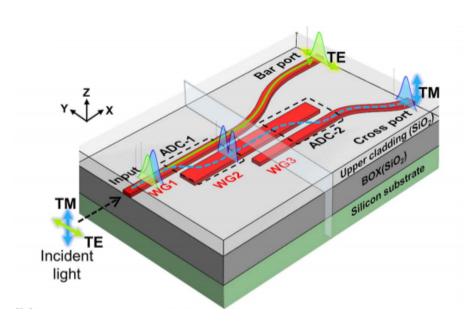


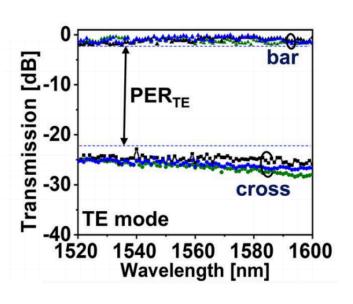
- ✓ low temperature dependence
- √ good process tolerance
- ✓ scalable
- ✓ Low phase errors
- small footprint

### Applications – Communications

### **Efficient broadband polarisation splitter**

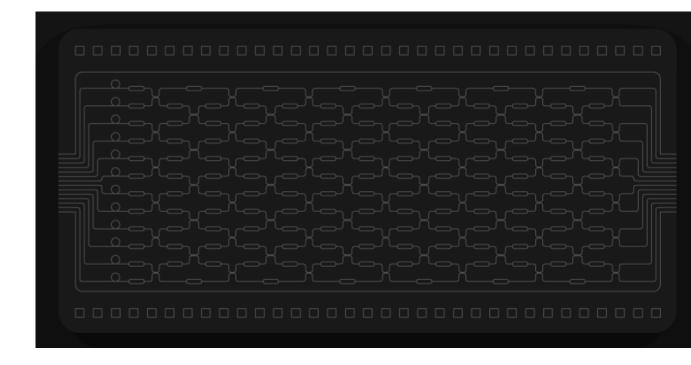








# **Quantum Computing**



### Applications - Quantum

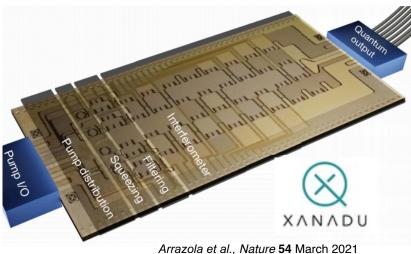
### Towards an optical quantum computer



### **Key requirements include:**

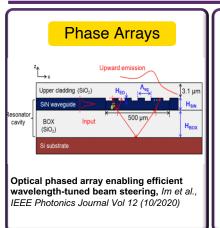
- Every Photon counts=> low loss circuitry
- High phase stability=> No moveable parts
- Small size components=> integrated on a chip
- Scalable to high volumes=> Wafer technology

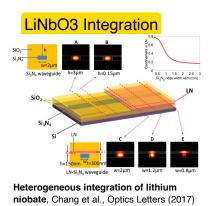


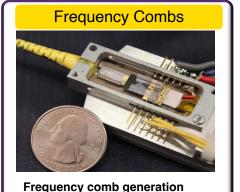


### **Used cases examples of LIGENTEC platform**



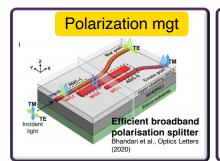


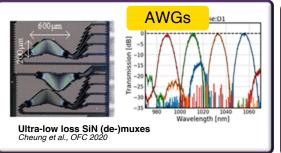


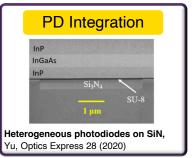


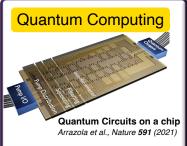
B. Shen, et al. Nature 582 (2020)











### Open Access

### **Seamless journey from Idea to Volumes**



### **Fast prototyping**

- Established technology
- Fixed layer stack
- Extensive PDK
- Regular MPW runs
- Custom runs
- Design / layout support
- Characterization
- Packaging support

### **Custom Development**

- Engineering studies
- Layer stack adaptation
- Custom integrations

### **Ligentec Labs**

Early technology access

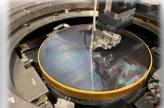
### **Pilot Fabrication**

Pilot and niche quantities

#### Volume Fabrication

- Large volumes
- High-capacity wafer fab and fully automated testing
- Automotive quality system



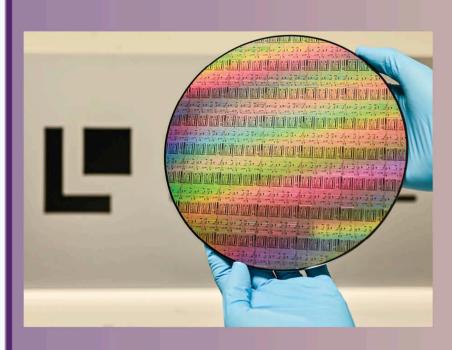


Pillars to assist ideas to the market

Open access, low entry barrier

High flexibility & competence

Quality and supply guarantee

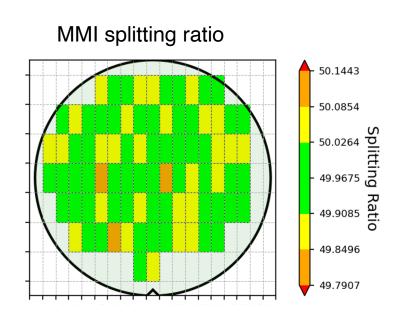


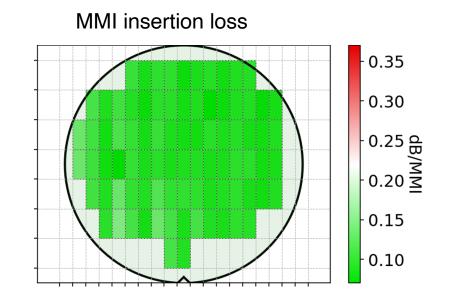
## **New PIC Partnership!**

"LIGENTEC and X-FAB collaboration creates Europe's largest capacity foundry service for integrated photonic circuits"

CLICK TO READ THE PRESS RELEASE





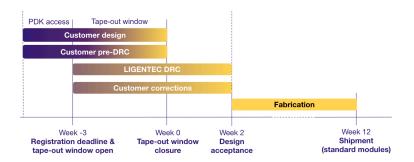


### You are not left alone

### **MPW runs**



### MPW process flow and support services



- Access to LIGENTEC PDK
- Training session on LIGENTEC PDK
- Training webinar on MPW submission
- Application engineering support
- DRC (design rule check) for manufacturability
- Post fabrication review session

### Frequent MPW runs

MPW number	SiN thickness	Registration deadline	Design submission window	Expected shipping date for base module
LGT-MPW-AN800-20	800nm	01/11/21	01/11/21-22/11/21	28/03/22
LGT-MPW-AN800-21	800nm	15/12/21	15/12/21-22/01/22	14/04/22
LGT-MPW-AN800-22	800nm	01/03/22	01/03/22-22/03/22	14/06/22
LGT-MPW-AN800-23	800nm	01/06/22	01/06/22-22/06/22	14/09/22
LGT-MPW-AN800-24	800nm	01/09/22	01/09/22-22/09/22	14/12/22
LGT-MPW-AN150-11	150nm	15/12/21	15/12/21-22/01/22	14/04/22
LGT-MPW-AN150-12	150nm	01/03/22	01/03/22-22/03/22	14/06/22
LGT-MPW-AN150-13	150nm	01/06/22	01/06/22-22/06/22	14/09/22
LGT-MPW-AN150-14	150nm	01/09/22	01/09/22-22/09/22	14/12/22
LGT-MPW-AN400-02	400nm	01/03/22	01/03/22-22/03/22	14/06/22

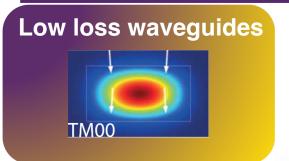
Typically 5 runs per year

Up to date schedule: ligentec.com/mpw

LIGENTEC PROPRIETARY

### **Low Loss SiN - Platform Overview**

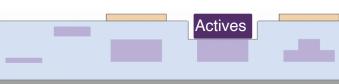




## MPW / Dedicated runs Short turn around

Flexible R&D line Volume line





### **Actives Integration**







### Low loss optical I/O

